

DOUBLE SIDED CHIP PACKAGE

ABSTRACT

A double sided chip package is disclosed. The package includes a LOC leadframe having a plurality of leads. Each lead is outwardly divided into a supporting portion extended between a bottom chip and a upper chip for supporting both chips, an inner connecting portion sealed by a package body for electrically connecting the bottom chip and the upper chip to the LOC leadframe by wire-bonging, and an outer portion exposed from the package body. So the double sided chip package has the benefits of a less warping, a stronger lead bonding, and a well-balancing molding flow.